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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE THE APPLICATION OF

Anslow et al.

SERIAL NO.: 09/451,127

FILED: November 30, 1999

FOR: HIGH DENSITY PRINTED WIRING BOARD
HAVING IN-VIA SURFACE MOUNTING PADS

) Examiner: J. Norris

) Group Art Unit:

) Docket No.: 476-1859

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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Commissioner for Patents, United States Patent and Trademark Office, Washington DC 20231, Box Responses, on May 31, 2002.

Name of person signing: Kathy Kurek
Signature _____

Kathy Kurek

**AMENDMENT AND RESPONSE TO OFFICE ACTION
DATED APRIL 24, 2002**

Commissioner for Patents
2900 Crystal Drive
Arlington, Virginia 22202-3513

Dear Sir:

In response to the Examiner's further office action of April 24, 2002, it is requested that the application be amended as follows:

In the Claims:

Amend Claim 4 as follows:

4. (Twice Amended). A printed circuit board comprising:

- a) a plurality of spaced apart circuit layers;
- b) a drill or laser formed blind hole/via extending between a surface circuit layer and at least one other circuit layer, said blind hole/via having an

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electrical connect layer which electrically connects said surface circuit layer to said at least one other circuit layer;

c) a reflow pad for mounting a component to the surface circuit layer, said reflow pad extending over a surface part of said electrical connect layer, and also extending over the blind hole/via; and

d) an electro-conductive material filling the blind hole/via.

Cancel ~~Claims 6 and 8~~ without prejudice, as the subject matter of those claims has been incorporated into amended Claim 4.

Cancel Claim ~~7~~ without prejudice as it is incompatible with amended Claim 4.

Remarks

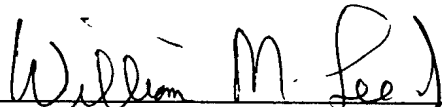
Reconsideration of the application is requested in view of the amendments above and the comments which follow.

The Examiner has indicated the allowability of the subject matter of Claim 8. Accordingly, Claim 4 has been amended to incorporate that novel subject matter (and Claim 6). Claim 5 remains in its present form, and Claims 6 and 8 have been cancelled in view of the incorporation into Claim 4. Finally, Claim 7 has been deleted since it is incompatible with Claim 4, as amended. Claims 4 and 5 remain in the application.

Given the incorporation of the allowable subject matter of Claim 8 into independent Claim 4, it is submitted that this application is now fully in condition for allowance, and the Examiner's further and favorable reconsideration in that regard is urged.

Respectfully submitted,

Date: May 31, 2002



William M. Lee, Jr.
Registration No. 26,935

Lee, Mann, Smith, McWilliams, Sweeney
& Ohlson
P.O. Box 2786
Chicago, Illinois 60690-2786
(312) 368-1300 Telephone
(312) 368-0034 Facsimile